MPX2300DT1

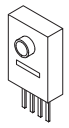
Chip Pak High Volume Pressure Sensor for Disposable, Backside Pressure Applications

PRESSURE SENSORS

Motorola has developed a low cost, high volume, miniature pressure sensor package which is ideal as a sub–module component or a disposable unit. The unique concept of the Chip Pak allows great flexibility in system design while allowing an economic solution for the designer. This new chip carrier package uses Motorola's unique sensor die with its piezoresistive technology, along with the added feature of on–chip, thin–film temperature compensation and calibration.

Features:

- Low Cost
- Patented piezoresistive strain gauge implant, temperature compensation and calibration all integrated on a single, monolithic sensor die.
- Pressure Range Available: 0–300 mmHg
- Polysulfone (Mindell S–1000) Case Material (Medical, Class VI Approved)



CHIP PAK ELEMENT
CASE 423A–03

PIN NUMBER			
1	V_S	3	S–
2	S+	4	Gnd

Motorola is offering the Chip Pak option package. Application–specific parts will have an "SPX" prefix, followed by a four digit number, unique to the specific customer. Devices will be shipped in a tape and reel packaging.

NOTE: The die and wire bonds are exposed on the front side of the Chip Pak (pressure is applied to the backside of the device). Front side die and wire protection must be provided in the customer's housing. Use caution when handling the devices during all processes.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Overpressure (Backside)	P_{max}	125	PSI
Burst Pressure	P_{burst}	1000	kPa
Supply Voltage	V_{Smax}	10	Vdc
Storage Temperature	T_{stg}	–25 to +85	°C
Operating Temperature	T_A	+15 to +40	°C

Motorola's MPX2300DT1 Pressure Sensors. Motorola's MPX2300DT1 pressure sensor has been designed for medical usage by combining the performance of Motorola's shear stress pressure sensor design and the use of biomedically approved materials. Materials with a proven history in medical situations have been chosen to provide a sensor that can be used with confidence in applications, such as invasive blood pressure monitoring. It can be sterilized using ethylene oxide. The portions of the pressure sensor that are required to be biomedically approved are the rigid housing and the gel coating.

The rigid housing is molded from a white, medical grade polysulfone that has passed extensive biological testing including: tissue culture test, rabbit implant, hemolysis, intracutaneous test in rabbits, and system toxicity, USP.

A silicone dielectric gel that has been used extensively in implants covers the silicon piezoresistive sensing element. The gel is a nontoxic, nonallergenic polymer system which passes pyrogen testing, as well as meeting all USP XX Biological Testing Class VI requirements. The properties of the gel allow it to transmit pressure uniformly to the diaphragm surface, while isolating the internal electrical connections from the corrosive effects of fluids, such as saline solution. The gel provides electrical isolation sufficient to withstand defibrillation testing, as specified in the proposed Association for the Advancement of Medical Instrumentation (AAMI) Standard for blood pressure transducers. A biomedically approved opaque filler in the gel prevents bright operating room lights from affecting the performance of the sensor.

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REV 3

OPERATING CHARACTERISTICS (V_S = 6 Vdc, T_A = 25°C unless otherwise noted)

Characteristics	Symbol	Min	Typ	Max	Unit
Pressure Range	P_{OP}	0	—	300	mmHg
Supply Voltage(8)	V_S	—	6.0	10	Vdc
Supply Current	I_o	—	1.0	—	mAdc
Zero Pressure Offset	V_{off}	–0.75	—	0.75	mV
Sensitivity	—	4.95	5.0	5.05	µV/V/mmHg
Full Scale Span(1)	V_{FSS}	2.976	3.006	3.036	mV
Linearity + Hysteresis(2)	—	– 1.5	—	1.5	$\%V_{FSS}$
Accuracy(10) V_S = 6 V, P = 101 to 200 mmHg	—	– 1.5	—	1.5	%
Accuracy(10) V_S = 6 V, P = 201 to 300 mmHg	—	– 3.0	—	3.0	%
Temperature Effect on Sensitivity	TCS	–0.1	—	+0.1	%/°C
Temperature Effect on Full Scale Span(3)	TCV_{FSS}	–0.1	—	+0.1	%/°C
Temperature Effect on Offset(4)	TCV_{off}	–9.0	—	+9.0	µV/°C
Input Impedance	Z_{in}	1800	—	4500	Ω
Output Impedance	Z_{out}	270	—	330	Ω
R_{CAL} (150 kΩ)(9)	R_{CAL}	97	100	103	mmHg
Response Time(5) (10% to 90%)	t_R	—	1.0	—	ms
Temperature Error Band	—	0	—	85	°C
Stability(6)	—	—	±0.5	—	$\%V_{FSS}$

MECHANICAL CHARACTERISTICS

Characteristics	Symbol	Min	Typ	Max	Unit
Weight (Case 423)	—	—	170	—	mg
Warm–Up	—	—	15	—	Sec

NOTES:

1. Measured at 6.0 Vdc excitation for 100 mmHg pressure differential. V_{FSS} and FSS are like terms representing the algebraic difference between full scale output and zero pressure offset.
2. Maximum deviation from end–point straight line fit at 0 and 200 mmHg.
3. Slope of end–point straight line fit to full scale span at 15°C and +40°C relative to +25°C.
4. Slope of end–point straight line fit to zero pressure offset at 15°C and +40°C relative to +25°C.
5. For a 0 to 300 mmHg pressure step change.
6. Stability is defined as the maximum difference in output at any pressure within P_{OP} and temperature within +10°C to +85°C after:
   a. 1000 temperature cycles, –40°C to +125°C.
   b. 1.5 million pressure cycles, 0 to 300 mmHg.
7. Operating characteristics based on positive pressure differential relative to the vacuum side (gauge/differential).
8. Recommended voltage supply: 6 V ± 0.2 V, regulated. Sensor output is ratiometric to the voltage supply. Supply voltages above +10 V may induce additional error due to device self–heating.
9. Offset measurement with respect to the measured sensitivity when a 150k ohm resistor is connected to V_S and S+ output.
10. Accuracy is calculated using the following equation:
    $Error_p = \{[V_p – Offset)/(Sens_{Nom}*V_{EX})] – P\}/P$
    Where: V_p = Actual output voltage at pressure P in microvolts (µV)
    Offset = Voltage output at P = 0mmHg in microvolts (µV)
    $Sens_{Nom}$ = Nominal sensitivity = 5.01 µV/V/mmHg
    V_{EX} = Excitation voltage
    P = Pressure applied to the device

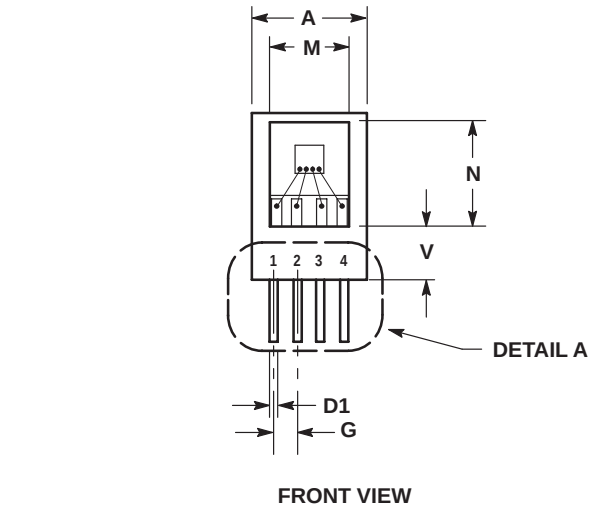
ORDERING INFORMATION

The MPX2300DT1 silicon pressure sensors are available in tape and reel.

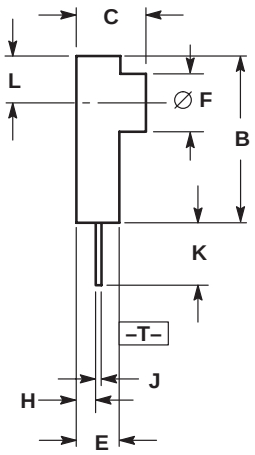
Device Type Options	Case No.	MPX Series Order No.	Marking
Tape and Reel	423A–03		Date Code, Lot ID

Device	Reel Size	Tape Width	Quantity
MPX2300DT1	330 mm	24 mm	1000 pc/reel

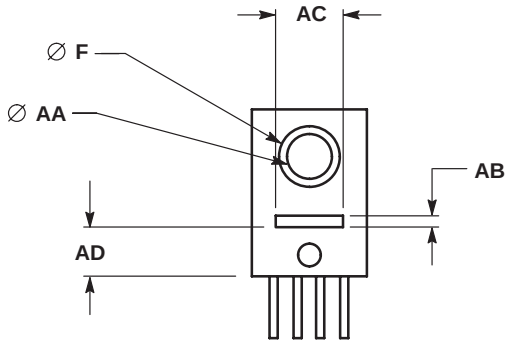
PACKAGE DIMENSIONS



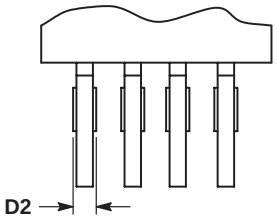
FRONT VIEW



END VIEW



BACK VIEW



DETAIL A

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.240	0.260	6.10	6.60
B	0.350	0.370	8.89	9.40
C	0.140	0.150	3.56	3.81
D1	0.012	0.020	0.30	0.51
D2	0.014	0.022	0.36	0.56
E	0.088	0.102	2.24	2.59
F	0.123	0.128	3.12	3.25
G	0.045	0.055	1.14	1.40
H	0.037	0.047	0.94	1.19
J	0.007	0.011	0.18	0.28
K	0.120	0.140	3.05	3.56
L	0.095	0.105	2.41	2.67
M	0.165	0.175	4.19	4.45
N	0.223	0.239	5.66	6.07
V	0.105	0.115	2.67	2.92
AA	0.095	0.107	2.41	2.72
AB	0.015	0.035	0.38	0.89
AC	0.120	0.175	3.05	4.45
AD	0.100	0.115	2.54	2.92

STYLE 1:
PIN 1. V_{CC}
2. +OUT
3. –OUT
4. GROUND

CASE 423A–03
ISSUE C

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